

TECHNICAL REPORT



**Mechanical structures for electrical and electronic equipment – Dimensions of
mechanical structures of the 482,6 mm (19 in) series
Part 3-1: Technological schemes and applications**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MECHANICAL STRUCTURES FOR ELECTRICAL AND
ELECTRONIC EQUIPMENT – DIMENSIONS OF MECHANICAL
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A list of all parts in the IEC 60297 series, published under the general title *Mechanical structures for electrical and electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series*, can be found on the IEC website.

Future documents in this series will carry the new general title as cited above. Titles of existing documents in this series will be updated at the time of the next edition.

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INTRODUCTION

The IEC 60297 series contains dimensional definitions of the entire mechanical structure layers from level 1 to level 4 for electrical and electronic equipment practices. Nowadays, the IEC 60917-1 generic standard defines all the elements and components in the mechanical structure layers from level 1 to level 4, and they are adopted for the IEC 60917-2 (metric) series. The original concept of the mechanical structure layers was established in DIN 41494 and introduced into the former IEC 297 series, later republished as the IEC 60297 series. Therefore, the second edition of IEC 60917-1:2019 (generic) categorizes the existing IEC 60297 series as a "conventional standard (legacy system)", which contains the detail dimensions of the structure levels from level 1 to level 4 as well as the structure levels of the IEC 60917-2 series (metric).

Applications of the IEC 60297 series are divided into two different perceptions by the users:

- a) the traditional 19-inch racks and chassis configurations, and
- b) the 19-inch subrack system.

The latter has been providing effective and rational solutions for the critical issues on interconnection and packaging for electronic equipment, which have been in a close relationship with the IEC connector standards of IEC SC 48B, in the microelectronics era since the 1960s.

In the 1980s, the 19-inch subrack system was adopted as the mechanical specifications for open computer bus standards in the IEEE and other manufacturers' associations or industrial consortia. In such fields, not only newly developed high-performance connectors have been applied, but also advanced mechanical features have been developed, based on the 19-inch subrack system. These new technologies have been standardized, and their efforts considered as development for extended specifications for the 19-inch subrack system in IEC SC 48D.

From these points of view, this Technical Report has been prepared to provide the following information, not only for users of the IEC 60297 series standards, but also for the engineers who will develop new architectures or hardware for advanced ICT equipment or systems for the current IoT or Industry 4.0 era:

- information on technological schemes of the IEC 60297 series standards, which have been in development for over 40 years in IEC TC 48/SC 48D. (In the market for industrial electronics and information and communication technology (ICT), there are active users who take the two different approaches regarding the application or adoption of the technologies from the IEC 60297 series standards);
- the technological background of the standards, and the principles or concepts, which had been adopted to cope with the technological evolutions through the development process of the IEC 60297 series standards in IEC SC 48D;
- in standardization for mechanical structures for electrical and electronic equipment in IEC SC 48D, IEC 60917-1 has been published as the generic standard for modular order for the development of mechanical structures for electrical and electronic equipment practices. The IEC 60297 series also considered that the dimensions of the mechanical structure are partly in accordance with IEC 60917-1. This document clarifies the relationship between the IEC 60917 series and the IEC 60297 series;
- to introduce the domain of each part of the IEC 60297 series for structures for electrical and electronic equipment.

Annex A introduces applicable connectors for the 19-inch subrack system, including newly developed high-performance connectors which are not (yet) published as IEC SC 48B standards.

Annex B introduces relationships and compatibilities between the 19-inch subrack system standards in IEC SC 48D, the IEEE standards for the 19-inch subrack and plug-in units, and other industrial standards for the mechanical specifications. It also shows outlines of the extended mechanical features adopted for the 19-inch subrack system. These features include the implementations of the mezzanine cards and the conduction cooled system, and they are not yet defined in IEC SC 48D standards.

Through the study of the additional information given in Annex A and Annex B, further prospects on applications of the 19-inch subrack system will be seen, and the directions of the next standards development in IEC TC 48/SC 48D will be provided.

MECHANICAL STRUCTURES FOR ELECTRICAL AND ELECTRONIC EQUIPMENT – DIMENSIONS OF MECHANICAL STRUCTURES OF THE 482,6 mm (19 in) SERIES

Part 3-1: Technological schemes and applications

1 Scope

This part of IEC 60297 provides information on the technological schemes of the IEC 60297 series, and shows how to apply the 19-inch series standards for the mechanical structure practices for electrical and electronic equipment.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60297-3-100:2008, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-100: Basic dimensions of front panels, subracks, chassis, racks and cabinets*

IEC 60297-3-101:2004, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-101: Subracks and associated plug-in units*

IEC 60297-3-102:2004, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-102: Injector/extractor handle*

IEC 60297-3-103:2004, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-103: Keying and alignment pin*

IEC 60297-3-104:2006, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-104: Connector dependent interface dimensions of subracks and plug-in units*

IEC 60297-3-105:2008, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-105: Dimensions and design aspects for 1U high chassis*

IEC 60297-3-106:2010, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-106: Adaptation dimensions for subracks and chassis applicable with metric cabinets or racks in accordance with IEC 60917-2-1*

IEC 60297-3-107:2012, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-107: Dimensions of subracks and plug-in units, small form factor*

IEC 60297-3-108:2014, *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-108: Dimensions of R-type subracks and plug-in units*

IEC 60297-3-109:2015, *Mechanical structures for electrical and electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-109: Dimensions of chassis for embedded computing devices*

IEC 60297-3-110:2018, *Mechanical structures for electrical and electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-110: Residential racks and cabinets for smart houses*

IEC 60603-2, *Connectors for frequencies below 3 MHz for use with printed boards – Part 2: Detail specification for two-part connectors with assessed quality, for printed boards, for basic grid of 2,54 mm (0,1 in) with common mounting features*

IEC 60917-1, *Modular order for the development of mechanical structures for electrical and electronic equipment practices – Part 1: Generic standard*

IEC 60917-2:1992, *Modular order for the development of mechanical structures for electronic equipment practices – Part 2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice*

IEC 60917-2-1:1993, *Modular order for the development of mechanical structures for electronic equipment practices – Part 2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Section 1: Detail specification – Dimensions for cabinets and racks*

IEC 60917-2-2:1994, *Modular order for the development of mechanical structures for electronic equipment practices – Part 2: Sectional specification – Interface co-ordination dimensions for the 25 mm equipment practice – Section 2: Detail specification – Dimensions for subracks, chassis, backplanes, front panels and plug-in units*

IEC 61076-4-100, *Connectors for electronic equipment – Part 4-100: Printed board connectors with assessed quality – Detail specification for two-part connector modules having a grid of 2,5 mm for printed boards and backplanes*

IEC 61076-4-101, *Connectors for electronic equipment – Part 4-101: Printed board connectors with assessed quality – Detail specification for two-part connector modules, having a basic grid of 2,0 mm for printed boards and backplanes in accordance with IEC 60917*

IEC 61076-4-113, *Connectors for electronic equipment – Printed board connectors – Part 4-113: Detail specification for two-part connectors having 5 rows with a grid of 2,54 mm for printed boards and backplanes in bus applications*

IEC 61076-4-116, *Connectors for electronic equipment – Product requirements – Part 4-116: Printed board connectors – Detail specification for a high-speed two-part connector with integrated shielding function*

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IEEE 1101.1-1998, *IEEE Standard for Mechanical Core Specifications for Microcomputers Using IEC 603-2 Connectors*

IEEE 1101.10-1996, *IEEE Standard for Additional Mechanical Specifications for Microcomputers Using the IEEE 1101.1-1998 Equipment Practice*

IEEE 1101.11-1998, *IEEE Standard for Mechanical Rear Plug-in Units Specifications for Microcomputers Using IEEE 1101.1 and IEEE 1101.10 Equipment Practice*

IEEE 1101.2-1992, *IEEE Standard for Mechanical Core Specifications for Conduction-Cooled Eurocards*

IEEE 1301.4-1996, *IEEE Standard for a Metric Equipment Practice for Microcomputers – Coordination Document for Mezzanine Cards*

IEEE 1386-2001, *IEEE Standard for a Common Mezzanine Card Family: CMC*²⁰

IEEE 1386.1-2001, *IEEE Standard Physical and Environmental Layers for PCI Mezzanine Cards: PMC*²¹

ANSI/EIA RS310-C 1971 *Rack, Panels and Associated Equipment*

ANSI/VITA 1-1994 (S2001), *VME64*

ANSI/VITA 1.1-1997 (S2001), *VME64 Extensions*

ANSI/VITA 20-2005 (S2018), *Conduction Cooled PMC*

ANSI/VITA 32-2003 (S2014), *Processor PMC*

ANSI/VITA 35-2000 (S2021), *PMC-P4 Pin Out Mapping to VME P0 and VME64x P2*

ANSI/VITA 39-2003 (S2022), *PCI-X for PMC and Processor PMC*

ANSI/VITA 42.0-2021, *XMC: Switched Mezzanine Card (XMC) Auxiliary Standard*

ANSI/VITA 42.1-2006 (S2022), *XMC: Parallel RapidIO 8/16 LP-LVDS Protocol Layer Standard*

ANSI/VITA 42.2-2006 (S2018), *XMC: Serial RapidIO Protocol Layer Standard*

ANSI/VITA 42.3-2020, *XMC: PCI Express Protocol Layer Standard*

ANSI/VITA 42.6-2009 (R2015), *XMC: 10 Gigabit Ethernet 4-Lane Protocol Layer Standard*

²⁰ Withdrawn.

²¹ Withdrawn.

ANSI/VITA 46.0-2019, *VPX Baseline Standard*

ANSI/VITA 47-2005, *American National Standard for Environments, Design and Construction, Safety, and Quality for Plug-In Units Standard*

ANSI/VITA 48.0-2022, *Mechanical Standard for Microcomputers using Ruggedized Enhanced Design Implementation (REDI)*

ANSI/VITA 48.1-2020, *Mechanical Standard for VPX REDI Air Cooling*

ANSI/VITA 48.2-2020, *Mechanical Standard for VPX REDI Conduction Cooling*

ANSI/VITA 61.0-2022, *XMC 2.0*

PICMG 2.0 R3.0, *CompactPCI Specification*

PICMG 3.0 R3.0, *AdvancedTCA Base Specification*

PICMG MTCA.0 R2.0, *MicroTCA Base Specification*

DIN 41612-4:1987-10, *Steckverbinder für gedruckte Schaltungen, indirektes Stecken, Rastermaß 2,54 mm; Maße der Bauform H²²*

DIN 41494:1974-09, *Bauweise für elektronische Einrichtungen; Frontplatten und Gestelle, Maße²³*

MIL-STD-202, *Department of defense test method standard: electronic and electrical component parts*

MIL-STD-810, *Department of defense test method standard: environmental engineering considerations and laboratory tests*

VITA 30-2000 (S2022), *2mm Equipment Practice for Eurocard Systems*

VITA 41.0-2006 (S2022), *VXS VMEbus Switched Serial Standard*

The connector family according to DIN 41612, IEC 603-2 and the modular 19" system for mechanical structures of electronic equipment, 1984 April, Markt & Technik Verlag

²² Withdrawn.

²³ Withdrawn.